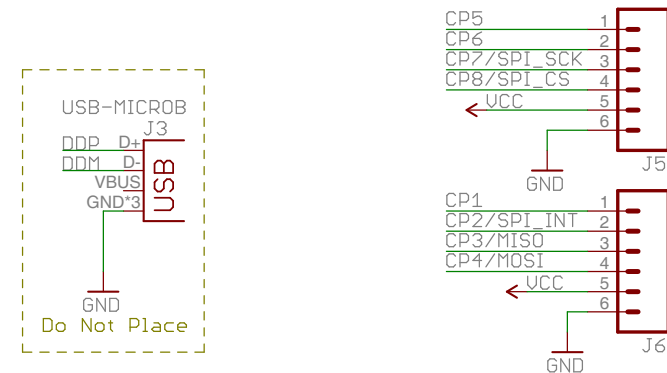
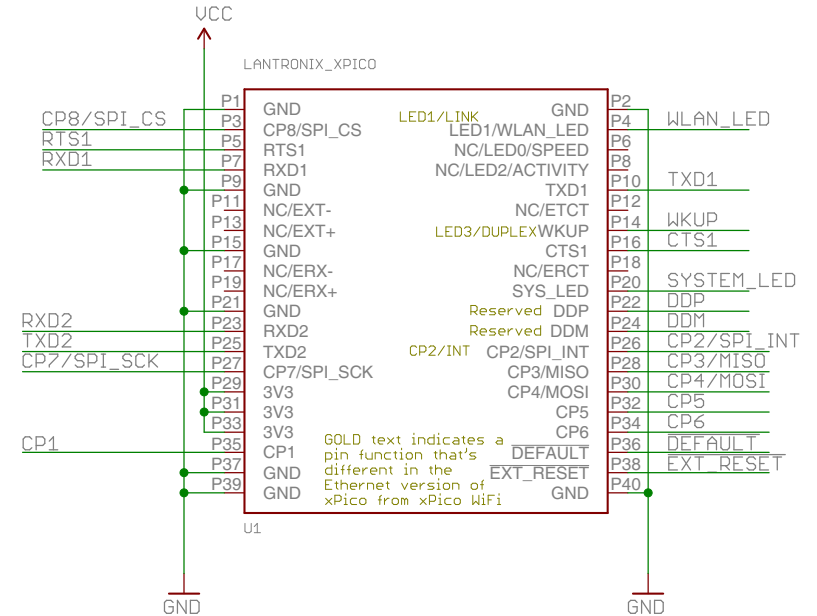
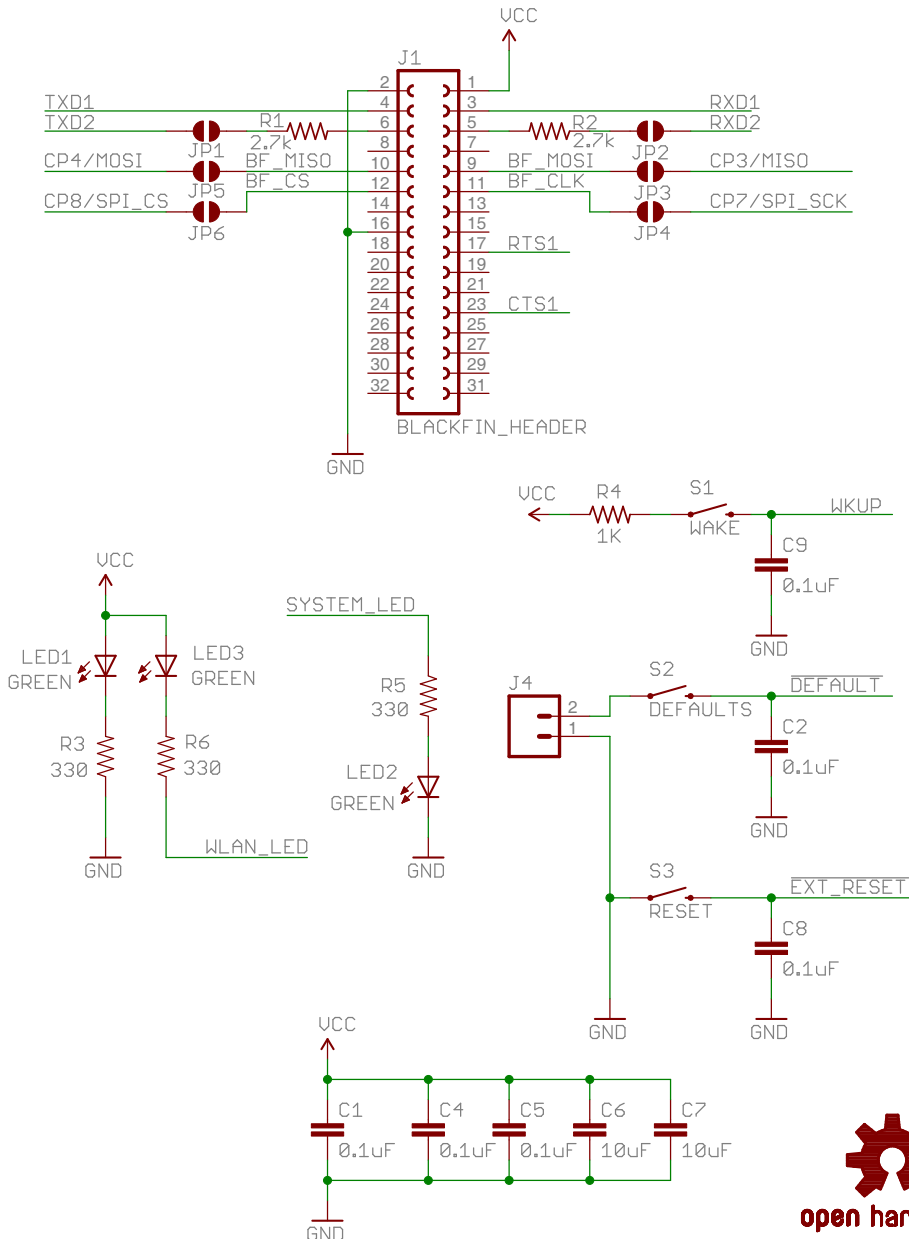


RCM-Comm Board v3.0

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05/30/16 BPS Removed big holes with copper ring, added same dia but normal holes, moved them so they sit better on other boards in the stack.



Designed for Tim Jump of Engineering^3
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Sheet: 1/1



RoHS Garbage